

L Number	Hits	Search Text	DB	Time stamp
1	166	loc with encapsula\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 16:41
2	111	(loc with encapsula\$4 ) and (@ad<20000816)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 16:40
7	833	257/686.ccls. and (@ad<20000816)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 16:41
8	254	(257/686.ccls. and (@ad<20000816)) and encapsula\$4	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 16:41

17	61	((chip or die) and (((remov\$3 or etch\$3 or delaminat\$3)and substrate)near encapsula\$4)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:17
18	0	4338/122. and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:00
20	136		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:07
21	196	257/707.ccls. and (encapsula\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:07
22	162	(257/707.ccls. and (encapsula\$)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:36
23	294	(chip or die) and ((fin\$2 or sink or spreader) near encapsula\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:17
24	225	((chip or die) and ((fin\$2 or sink or spreader) near encapsula\$)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:34
25	28	(chip or die) and ((encapsula\$ and substrate) with (key or interlock\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:39
26	16	((chip or die) and ((encapsula\$ and substrate) with (key or interlock\$3))) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:38
27	54	(chip or die) and ((mold near cavity) with (key or interlock\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:43
28	36	loc same (mold near cavity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:44

L Number	Hits	Search Text	DB	Time stamp
1	366	438/4.ccls. and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:00
2	27	(438/4.ccls. and (@ad<20000816)) and (encapsula\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:01
3	183	438/For.434.ccls. and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 12:43
4	1	(438/For.434.ccls. and (@ad<20000816)) and (encapsula\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 14:34
5	116	(flip near (chip or die)) and ((remov\$3 or etch\$3 or delaminat\$3) near encapsula\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 13:54
7	1	("5677566").PN.	USPAT	2003/02/19 12:49
6	75	((flip near (chip or die)) and ((remov\$3 or etch\$3 or delaminat\$3) near encapsula\$4)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 13:21
8	30	(chip or die) and (laser near encapsula\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 13:24
9	26	((chip or die) and (laser near encapsula\$4)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 13:25
10	315	(chip or die) and (laser with encapsula\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 13:25
11	240	((chip or die) and (laser with encapsula\$4)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 13:55
12	549	257/796.ccls. and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 13:50
13	7	(257/796.ccls. and (@ad<20000816)) and ((laser or remov\$3 or etch\$3 or delaminat\$3) near encapsula\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 13:53
14	2	((("6294830") or ("6251707"))).PN.	USPAT	2003/02/19 13:53
15	2	((("20020027010") or ("20020027265"))).PN.	US-PGPUB	2003/02/19 13:53
16	92	(chip or die) and ((remov\$3 or etch\$3 or delaminat\$3)and substrate)near encapsula\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 13:55